

Title (en)
PROCESS FOR ELECTROLESS DEPOSITION OF METALS USING HIGHLY ALKALINE PLATING BATH

Title (de)
VERFAHREN ZUR STROMLOSEN ABSCHIEDUNG VON METALLEN MITHILFE EINES STARK ALKALISCHEN PLATTIERUNGSBADES

Title (fr)
PROCÉDÉ POUR LE DÉPÔT AUTOCATALYTIQUE DE MÉTAUX UTILISANT UN BAIN DE PLACAGE HAUTEMENT ALCALIN

Publication
EP 2627798 A1 20130821 (EN)

Application
EP 11831881 A 20111012

Priority

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- US 201161457446 P 20110330
- US 34480010 P 20101013
- CA 2011001146 W 20111012

Abstract (en)
[origin: WO2012048412A1] A plating process using an electroless plating bath formed from two separate prepared component solutions. The component solutions mixed within 120 hours prior to plating operations, to provide a highly alkaline plating bath solution. One component solution of the two-part plating bath, is provided with a metal salt or source of plating ions, and which is initially kept in a separate solution from the second other prepared component solution. The second component solution contains formaldehyde, and preferably paraformaldehyde, used to reduce the metal salts into the metal to be deposited on a substrate. Each component solution further includes sodium hydroxide in concentrations selected so that when the two solutions are preferably mixed the final plating bath solution has a pH greater than 11.5.

IPC 8 full level
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CPC (source: EP KR US)
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Citation (search report)
See references of WO 2012048412A1

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